



ARCS 2013



26TH INTERNATIONAL CONFERENCE ON ARCHITECTURE OF COMPUTING SYSTEMS

ARCHITECTURAL ASPECTS FOR APPLICATION ACCELERATION

Prague, Czech Republic

February 19th – 22nd, 2013

<http://arcs2013.fit.cvut.cz>

CALL FOR PAPERS

Submission Deadline: October 14, 2012

The ARCS series of conferences has over 30 years of tradition reporting top notch results in computer architecture and operating systems research. This year's focus will be on architectural aspects for application acceleration. Like the previous conferences in this series, it continues to be an important forum for computer architecture research. In 2013 ARCS will be hosted by the Czech Technical University in Prague.

The proceedings of ARCS 2013 will be published in the Springer Lecture Notes on Computer Science (LNCS) series (pending). After the conference, authors of selected papers will be invited to submit an extended version of their contribution for publication in a special issue of the Journal of Systems Architecture. Also, the best paper and best presentation award will be presented at the conference.

Paper submission: Authors are invited to submit original, unpublished research papers on one of the following topics:

- Computer architecture topics such as multi-cores, memory systems, and parallel computing
- Adaptive system architectures such as reconfigurable systems in hardware and software
- Customization and application specific accelerators in heterogeneous architectures
- Organic and Autonomic Computing including both theoretical and practical results on self-organization, self-configuration, self-optimization, self-healing, and self-protection techniques
- Operating Systems including but not limited to scheduling, memory management, power management, and RTOS
- Energy-awareness, green computing
- System aspects of ubiquitous and pervasive computing such as sensor nodes, novel input/output devices, novel computing platforms, architecture modeling, and middleware
- Embedded systems including but not limited to architecture, communication, design methodologies, and applications
- Network Centric and Grid Computing

Submissions should be done through the link provided at the conference website <http://arcs2013.fit.cvut.cz/>. Papers should be submitted in pdf or postscript format. They should be formatted according to Springer LNCS style (see: <http://www.springer.de/comp/lncs/authors.html>) and not exceed 12 pages.

Workshop and Tutorial Proposals: Proposals for workshops and tutorials within the technical scope of the conference are solicited. Submissions should be done through email directly to the workshops and tutorials chair Mladen Berekovic (berekovic@c3e.cs.tu-bs.de).

Important Dates

Paper submission deadline:	October	14 (final deadline)
Workshop and tutorial proposals:	October	15, 2012
Notification of acceptance:	November	19, 2012
Camera ready papers:	December	16, 2012

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